

FEATURES

- Excellent character appearance.
- Case mold type.
- Touch pad.
- Black face (overlay) / White segment.
- RoHS compliant, Pb Free.

DESCRIPTION

The CTD1515LE-PD-BW is a Touch Pad with 15.0 mm X 15.0 mm icon LED display.

This device utilizes Super Bright Red LED chip which are made from AllnGaP on a transparent GaAs substrate.

The display has Black face (overlay), White segment.

This mold of display is attached with overlay.

DEVICE

PART NO.	DESCRIPTION		
CTD1515LE-PD-BW	Touch pad with LED Display		

RoHS Compliance

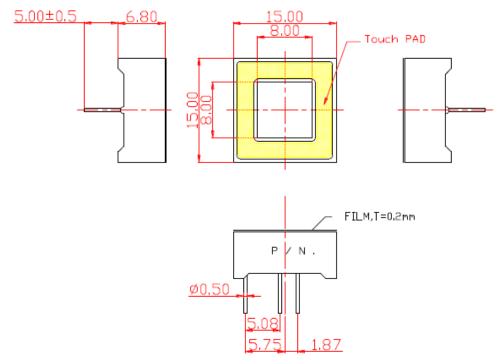


Pb free.





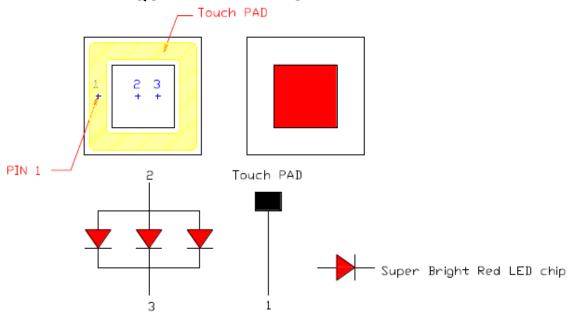
MECHANICAL DIMENSIONS



Notes:

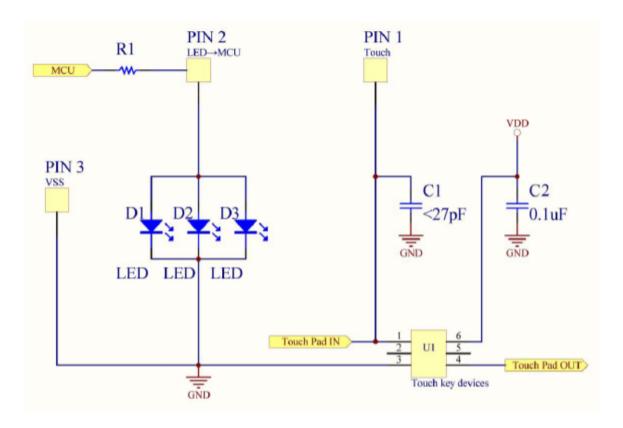
1. All dimensions are in millimeters (inches); tolerances are ±0.25mm (0.01") specified

TYPICAL INTERNAL EQUIVALENT CIRCUIT





APPLICATION CIRCUITS



INTERNAL COMPONENTS, NOT CUSTOMER ACCESSINLE.

FILM





LB: SUPER BRIGHT BLUE (AlGaInP/GaAs) ABOSULTE MAXIMUM RATING AT Ta=25°C

Parameter	Symbol	Maximum Rating	Unit	
Power dissipation per dice	P _{AD}	70	mW	
Derating liner from 25°C per dice	-	0.28	mA / °C	
Continuous forward current per dice	I _A F	25	mA	
Peak current per dice (duty cycle 1/10, 1kHz)	I PF	90	mA	
Reverse voltage per dice	VR	5	V	
Operating temperature	Topr	-25 to +85	°C	
Storage temperature	Tstg	-25 to +85	°C	

ELECTRICAL-OPTICAL CHARACTERISTICS AT Ta=25°C

Characteristic	Symbol	Condition	Min.	Type.	Max.	Unit
Forward Voltage	VF	I _F =2mA	ı	2.0	2.6	٧
Reverse Current	I _R	V _R =5V	-	-	10	μA
Peak Wavelength	λР	I _F =20mA	-	632	-	nm
Dominant Wavelength	λ _D	I _F =20mA	-	624	-	nm
Average Luminous Intensity	I _V	I _F =20mA	-	50	-	mcd
Spectral Radiation Bandwidth	Δλ	I _F =20mA	-	20	-	nm



LB: SUPER BRIGHT RED (AlGaInP/GaAs) CURVE TYPICAL ELECTRO-OPTICAL CHARACTERISTIC CURVE

Ta=25°C

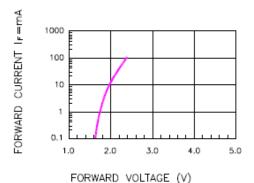
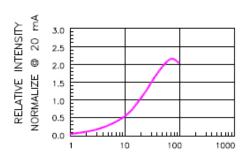


Fig.1 FORWARD CURRENT VS. FORWARD VOLTAGE



FORWARD CURRENT (mA)
Fig.2 RELATIVE INTENSITY VS. FORWARD CURRENT

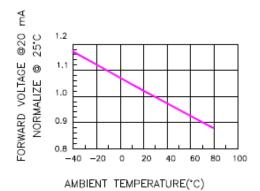
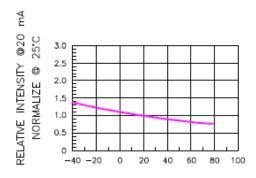


Fig.3 FORWARD VOLTAGE VS. TEMPERATURE



AMBIENT TEMPERATURE(*C)
Fig.4 RELATIVE INTENSITY VS. TEMPERATURE

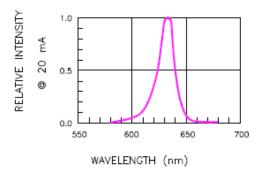
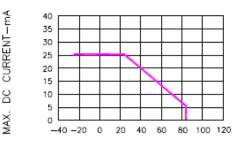


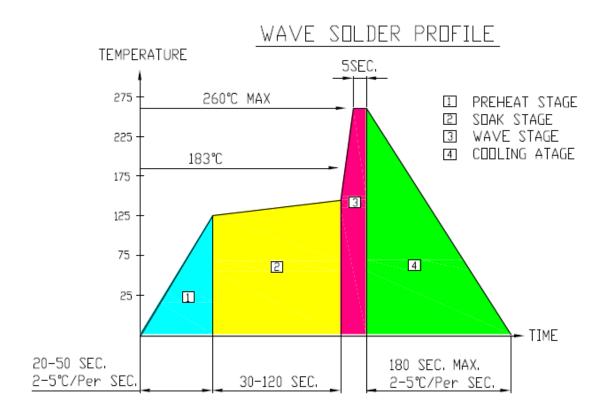
Fig.5 RELATIVE INTENSITY VS. WAVELENGTH



AMBIENT TEMPERATURE (TA)-*C
Fig.6 MAX. ALLOWABLE DC CURRENT
VS. AMBIENT TEMPERATURE



RECOMMEND SOLDERING PROFILE



NOTES

- Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
- 2. Peak wave soldering temperature between 245°C ~ 225°C for 3 sec (5 sec max)
- 3. No more than one wave soldering pass

SOLDERING IRON

 Basic spec is ≤4 sec when 260°C. If temperature is higher, time should be shorter (+10°C→1 sec). Power dissipation of Iron should be smaller than 15W, and temperature should be controllable. Surface temperature of the device should be under 230°C

REWORK

- Customer must finish rework within 3 sec under 350°C
- 2. The head of soldering iron cannot touch copper foil